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SN74CB3Q3125 Quadruple FET Bus Switch 2.5-V/3.3-V Low-Voltage, High-Bandwidth Bus Switch

1 Features

- High-Bandwidth Data Path (up to 500 MHz⁽¹⁾)
- 5-V Tolerant I/Os With Device Powered Up or Powered Down
- Low and Flat ON-State Resistance (r_{on}) Characteristics Over Operating Range ($r_{on} = 3 \Omega$ Typ)
- Rail-to-Rail Switching on Data I/O Ports
 - 0-V to 5-V Switching With 3.3-V V_{cc}
 - 0-V to 3.3-V Switching With 2.5-V V_{cc}
- Bidirectional Data Flow With Near-Zero Propagation Delay
- Low Input and Output Capacitance Minimizes Loading and Signal Distortion ($C_{io(OFF)} = 4 \text{ pF}$ Typ)
- Fast Switching Frequency ($f_{OE} = 20 \text{ MHz}$ Max)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ($I_{cc} = 0.3 \text{ mA}$ Typ)
- V_{cc} Operating Range From 2.3 V to 3.6 V
- Data I/Os Support 0-V to 5-V Signaling Levels (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V)
- Control Inputs Can Be Driven by TTL, 5-V, or 3.3-V CMOS Outputs
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- Supports Both Digital and Analog Applications: USB Interface, Differential Signal Interface, Bus Isolation, Low-Distortion Signal Gating

⁽¹⁾ For additional information regarding the performance characteristics of the CB3Q family, refer to the TI application report, *CBT-C, CB3T, and CB3Q Signal-Switch Families (SCDA008)*.

2 Applications

- IP Phones: Wired and Wireless
- Optical Modules
- Optical Networking: Video Over Fiber and EPON
- Private Branch Exchange (PBX)
- WiMAX and Wireless Infrastructure Equipment

3 Description

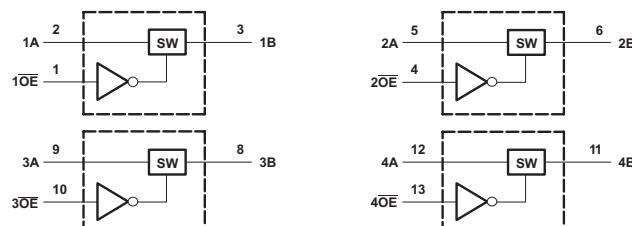
The SN74CB3Q3125 device is a high-bandwidth FET bus switch that uses a charge pump to elevate the gate voltage of the pass transistor, thus providing a low and flat ON-state resistance (r_{on}). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The SN74CB3Q3125 device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74CB3Q3125	VQFN (14)	3.50 mm × 3.50 mm
	SSOP (16)	4.90 mm × 3.90 mm
	TSSOP (16)	5.00 mm × 4.40 mm
	TVSOP (16)	4.40 mm × 3.60 mm

⁽¹⁾ For all available packages, see the orderable addendum at the end of the data sheet.

Logic Diagram (Positive Logic)



Pin numbers shown are for the DGV, PW, and RGY packages.



An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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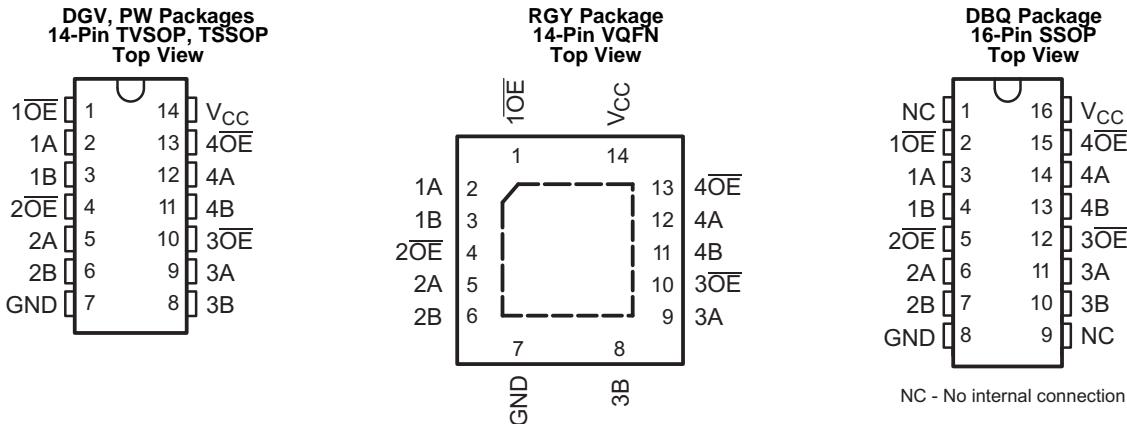
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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (March 2005) to Revision C	Page
• Added <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Detailed Description</i> section, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section.....	1
• Deleted <i>Ordering Information</i> table.	1

5 Pin Configuration and Functions



Pin Functions

NAME	PIN		I/O	DESCRIPTION
	DGV, PW, RGY	DBQ		
$\overline{1OE}$	1	2	I	Output Enable (Active Low)
1A	2	3	I/O	Channel 1A I/O 1A
1B	3	4	I/O	Channel 1B I/O 1B
$\overline{2OE}$	4	5	I	Output Enable (Active Low)
2A	5	6	I/O	Channel 2A I/O 2A
2B	6	7	I/O	Channel 2B I/O 2B
GND	7	8	—	Ground
3B	8	10	I/O	Channel 3B I/O 3B
3A	9	11	I/O	Channel 3A I/O 3B
$\overline{3OE}$	10	12	I	Output Enable (Active Low)
4B	11	13	I/O	Channel 4B I/O 4B
4A	12	14	I/O	Channel 4A I/O 4B
$\overline{4OE}$	13	15	I	Output Enable (Active Low)
NC	—	1, 9	—	No Connect
V _{CC}	14	16	—	Power

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	-0.5	4.6	V
V_{IN}	Control input voltage ⁽²⁾⁽³⁾	-0.5	7	V
$V_{I/O}$	Switch I/O voltage ⁽²⁾⁽³⁾⁽⁴⁾	-0.5	7	V
$I_{I/K}$	Control input clamp current	$V_{IN} < 0$	-50	mA
$I_{I/OK}$	I/O port clamp current	$V_{I/O} < 0$	-50	mA
I_{IO}	ON-state switch current ⁽⁵⁾		± 64	mA
	Continuous current through V_{CC} or GND		± 100	mA
T_J	Junction temperature		150	°C
T_{stg}	Storage temperature	-65	150	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages are with respect to ground, unless otherwise specified.
- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (4) V_I and V_O are used to denote specific conditions for $V_{I/O}$.
- (5) I_I and I_O are used to denote specific conditions for $I_{I/O}$.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	+2000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	+1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.3	3.6	V
V_{IH}	High-level control input voltage	$V_{CC} = 2.3$ V to 2.7 V	1.7	V
		$V_{CC} = 2.7$ V to 3.6 V	2	
V_{IL}	Low-level control input voltage	$V_{CC} = 2.3$ V to 2.7 V	0	V
		$V_{CC} = 2.7$ V to 3.6 V	0	
$V_{I/O}$	Data input and output voltage	0	5.5	V
T_A	Operating free-air temperature	-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* ([SCBA004](#)).

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾	SN74CB3Q3257				UNIT	
	DBQ (SSOP)	DGV (TSSOP)	PW (TSSOP)	RGY (VQFN)		
	16 PINS	14 PINS	14 PINS	14 PINS		
$R_{\theta JA}$	Junction-to-ambient thermal resistance	90	127	113	47	°C/W

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER	TEST CONDITIONS			MIN	TYP ⁽²⁾	MAX	UNIT
V_{IK}	$V_{CC} = 3.6 \text{ V}$, $I_I = -18 \text{ mA}$					-1.8	V
I_{IN} Control inputs	$V_{CC} = 3.6 \text{ V}$, $V_{IN} = 0 \text{ to } 5.5 \text{ V}$					± 1	μA
$I_{OZ}^{(3)}$	$V_{CC} = 3.6 \text{ V}$, $V_O = 0 \text{ to } 5.5 \text{ V}$, $V_I = 0$, $V_{IN} = V_{CC}$ or GND					± 1	μA
I_{off}	$V_{CC} = 0$, $V_O = 0 \text{ to } 5.5 \text{ V}$, $V_I = 0$					1	μA
I_{CC}	$V_{CC} = 3.6 \text{ V}$, $I_{I/O} = 0$, $V_{IN} = V_{CC}$ or GND			0.3	1		mA
$\Delta I_{CC}^{(4)}$ Control inputs	$V_{CC} = 3.6 \text{ V}$, One input at 3 V, Other inputs at V_{CC} or GND					30	μA
$I_{CCD}^{(5)}$ Per control input	$V_{CC} = 3.6 \text{ V}$, A and B ports open, Control input switching at 50% duty cycle			0.04	0.2		mA/MHz
C_{in} Control inputs	$V_{CC} = 3.3 \text{ V}$, $V_{IN} = 5.5 \text{ V}$, 3.3 V, or 0			2.5	3.5		pF
$C_{io(OFF)}$	$V_{CC} = 3.3 \text{ V}$, Switch OFF, $V_{IN} = V_{CC}$ or GND, $V_{I/O} = 5.5 \text{ V}$, 3.3 V, or 0			4	5		pF
$C_{io(ON)}$	$V_{CC} = 3.3 \text{ V}$, Switch ON, $V_{IN} = V_{CC}$ or GND, $V_{I/O} = 5.5 \text{ V}$, 3.3 V, or 0			8	10		pF
$r_{on}^{(6)}$	$V_{CC} = 2.3 \text{ V}$, TYP at $V_{CC} = 2.5 \text{ V}$	$V_I = 0$,	$I_O = 30 \text{ mA}$	4	8		Ω
		$V_I = 1.7 \text{ V}$,	$I_O = -15 \text{ mA}$	4	9		
	$V_{CC} = 3 \text{ V}$	$V_I = 0$,	$I_O = 30 \text{ mA}$	4	6		
		$V_I = 2.4 \text{ V}$,	$I_O = -15 \text{ mA}$	4	8		

(1) V_{IN} and I_{IN} refer to control inputs. V_I , V_O , I_I , and I_O refer to data pins.

(2) All typical values are at $V_{CC} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

(4) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

(5) This parameter specifies the dynamic power-supply current associated with the operating frequency of a single control input (see Figure 2).

(6) Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

6.6 Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

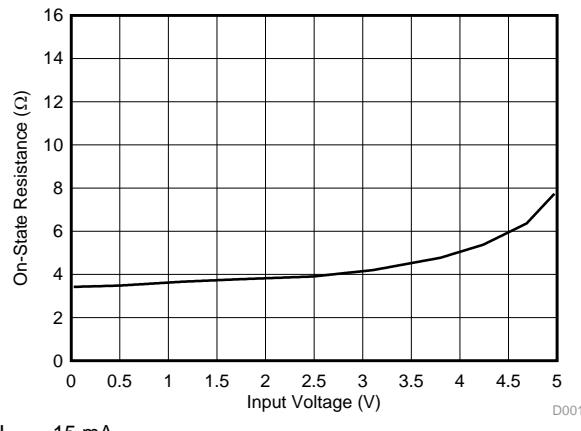
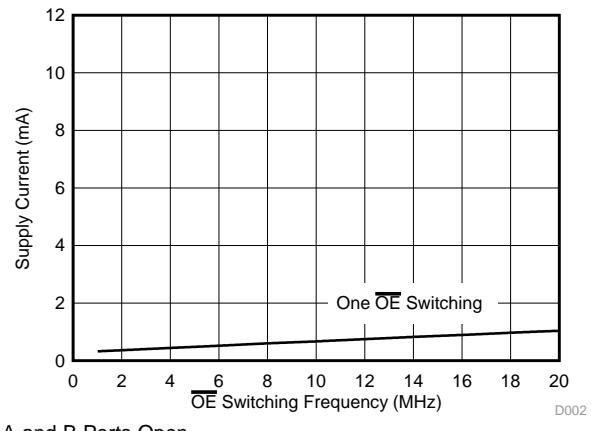
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$		$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
$f_{OE}^{(1)}$	\overline{OE}	A or B		10		20	MHz
$t_{pd}^{(2)}$	A or B	B or A		0.12		0.2	ns
t_{en}	\overline{OE}	A or B	1.5	6.7	1.5	6.6	ns
t_{dis}	\overline{OE}	A or B	1	4.6	1	5.3	ns

(1) Maximum switching frequency for control input ($V_O > V_{CC}$, $V_I = 5 \text{ V}$, $R_L \geq 1 \text{ M}\Omega$, $C_L = 0$)

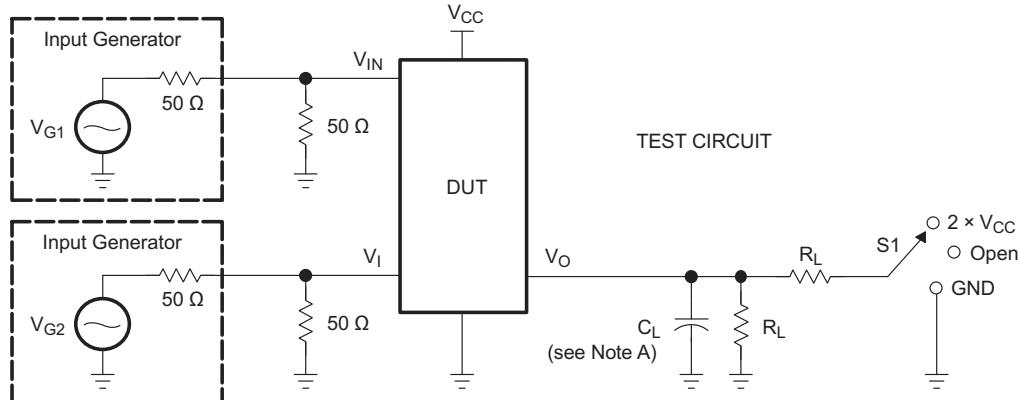
(2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

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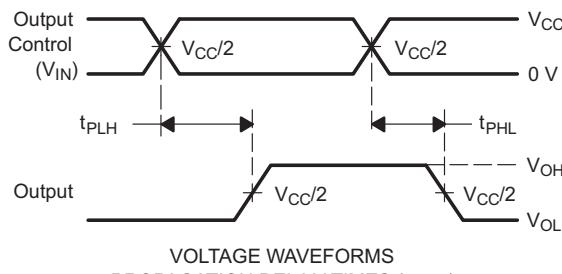
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www.ti.com**6.7 Typical Characteristics**At $T_A = 25^\circ\text{C}$ and $V_{CC} = 3.3\text{ V}$, unless otherwise noted.**Figure 1. Typical On-State Resistance vs Input Voltage****Figure 2. Typical Supply Current vs \overline{OE} Switching Frequency**

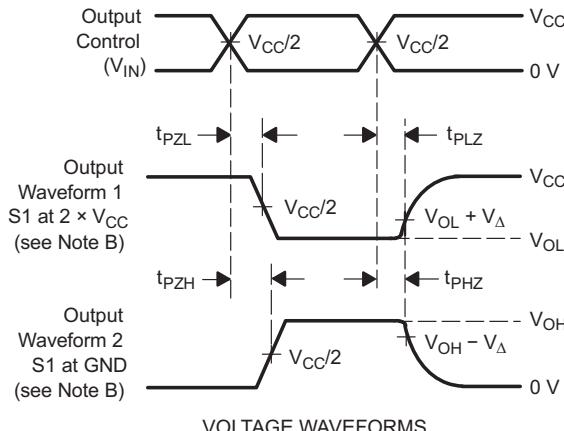
7 Parameter Measurement Information



TEST	V _{CC}	S1	R _L	V _I	C _L	V _Δ
t _{pd(s)}	2.5 V ± 0.2 V 3.3 V ± 0.3 V	Open Open	500 Ω 500 Ω	V _{CC} or GND V _{CC} or GND	30 pF 50 pF	
t _{PLZ/tPZL}	2.5 V ± 0.2 V 3.3 V ± 0.3 V	2 × V _{CC} 2 × V _{CC}	500 Ω 500 Ω	GND GND	30 pF 50 pF	0.15 V 0.3 V
t _{PHZ/tPZH}	2.5 V ± 0.2 V 3.3 V ± 0.3 V	GND GND	500 Ω 500 Ω	V _{CC} V _{CC}	30 pF 50 pF	0.15 V 0.3 V



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (t_{pd(s)})



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd(s)}. The t_{pd} propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- H. All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

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8 Detailed Description

8.1 Overview

The SN74CB3Q3125 device is a high-bandwidth FET bus switch utilizing a charge pump to elevate the gate voltage of the pass transistor, providing a low and flat ON-state resistance (r_{on}). The low and flat ON-state resistance allows for minimal propagation delay and supports rail-to-rail switching on the data input/output (I/O) ports. The SN74CB3Q3125 device also features low data I/O capacitance to minimize capacitive loading and signal distortion on the data bus. Specifically designed to support high-bandwidth applications, the SN74CB3Q3125 device provides an optimized interface solution ideally suited for broadband communications, networking, and data-intensive computing systems.

The SN74CB3Q3125 device is organized as four 1-bit bus switches with separate output-enable ($1\overline{OE}$, $2\overline{OE}$, $3\overline{OE}$, $4\overline{OE}$) inputs. It can be used as four 1-bit bus switches or as one 4-bit bus switch. When \overline{OE} is low, the associated 1-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When \overline{OE} is high, the associated 1-bit bus switch is OFF, and a high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry prevents damaging current backflow through the device when it is powered down. The device has isolation during power off.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

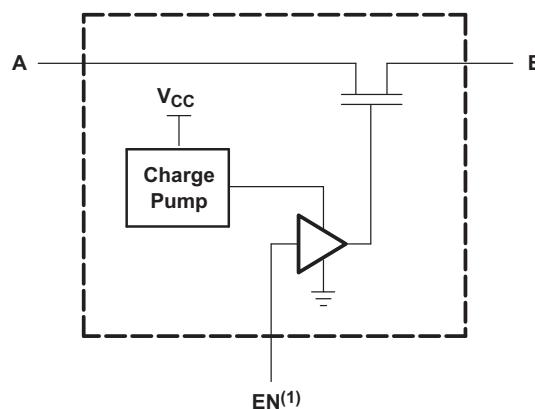
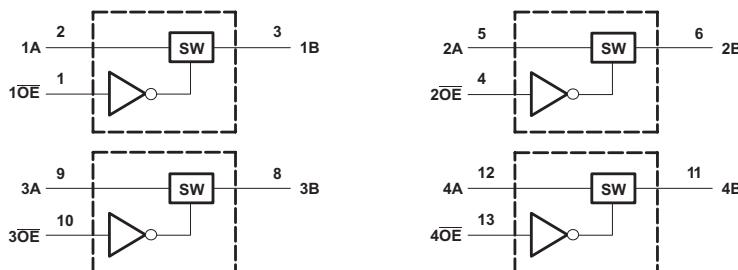


Figure 4. Simplified Schematic, Each FET Switch (SW)

8.2 Functional Block Diagram



8.3 Feature Description

The SN74CB3Q3125 device has a high-bandwidth data path (up to 500 MHz) and has 5-V tolerant I/Os with the device powered up or powered down. It also has low and flat ON-state resistance (r_{on}) characteristics over operating range ($r_{on} = 4\text{-}\Omega$ Typ).

The SN74CB3Q3125 device has rail-to-rail switching on data I/O ports for 0-V to 5-V switching with 3.3-V V_{CC} and 0-V to 3.3-V switching with 2.5-V V_{CC} as well as bidirectional data flow with near-zero propagation delay and low input/output capacitance that minimizes loading and signal distortion ($C_{io(OFF)} = 3.5\text{-pF}$ Typ).

The SN74CB3Q3125 device also provides a fast switching frequency ($f_{OE} = 20\text{-MHz}$ Max) with data and control inputs that provide undershoot clamp diodes as well as low power consumption ($I_{CC} = 0.6\text{-mA}$ Typ).

The V_{CC} operating range is from 2.3 V to 3.6 V and the data I/Os support 0-V to 5-V signal levels of (0.8 V, 1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V, 5 V).

The control inputs can be driven by TTL or 5-V or 3.3-V CMOS outputs, and I_{off} supports partial-power-down mode operation.

8.4 Device Functional Modes

Table 1 lists the functional modes for the SN74CB3Q3125 device.

Table 1. Function Table

INPUT \overline{OE}	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect

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9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74CB3Q3125 device can be used to control up to four channels simultaneously.

9.2 Typical Application

The application shown in [Figure 5](#) is a 4-bit bus being controlled. The \overline{OE} pins are used to control the chip from the bus controller. This is a very generic example and can apply to many situations. If an application requires less than 4 bits, be sure to tie the A side to either high or low on unused channels.

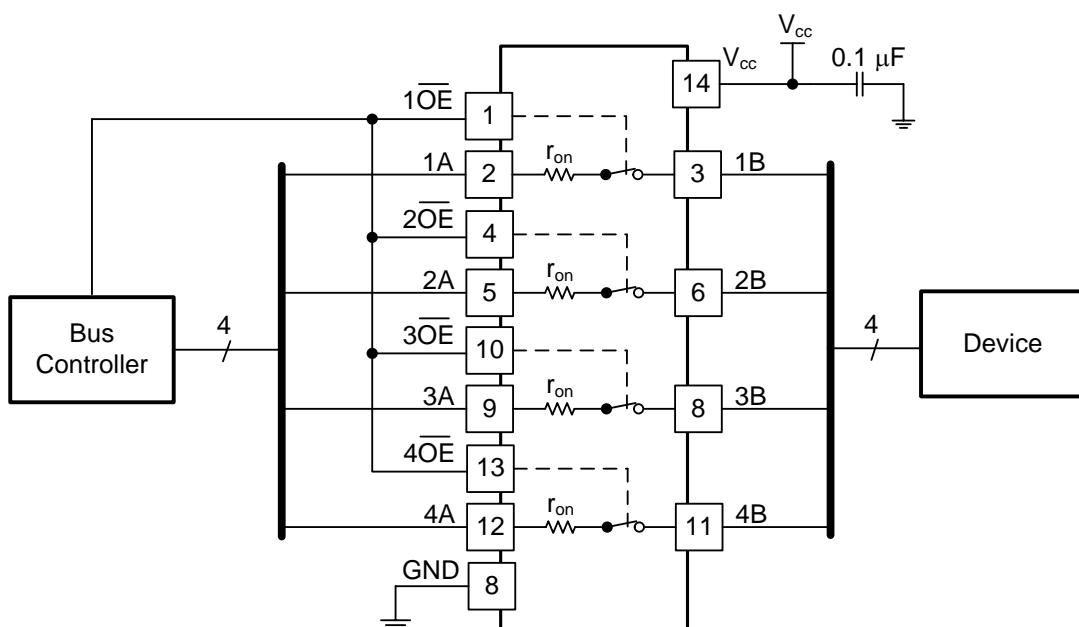


Figure 5. Typical Application of the SN74CB3Q3257

9.2.1 Design Requirements

The 0.1- μ F capacitor must be placed as close as possible to the SN74CB3Q3257 device.

Typical Application (continued)

9.2.2 Detailed Design Procedure

1. Recommended input conditions:
 - For specified high and low levels, see V_{IH} and V_{IL} in *Recommended Operating Conditions*
 - Inputs and outputs are overvoltage tolerant, which slows them to go as high as 5.5 V at any valid V_{CC}
2. Recommended output conditions:
 - Load currents must not exceed ± 64 mA per channel
3. Frequency selection criterion:
 - Added trace resistance or capacitance can reduce maximum frequency capability; use layout practices as directed in *Layout*

9.2.3 Application Curve

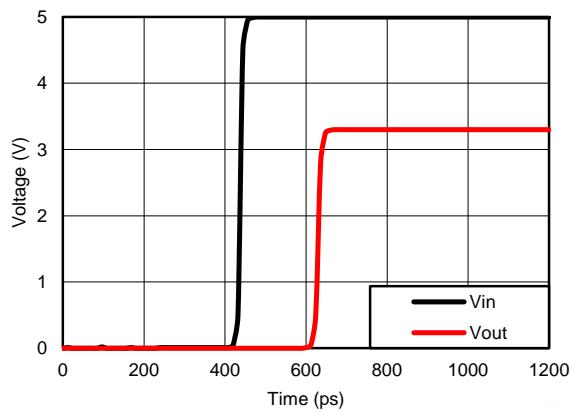


Figure 6. Propagation Delay (t_{pd}) Simulation Result at $V_{CC} = 3.3$ V

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating listed in the *Absolute Maximum Ratings* table.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μ F bypass capacitor is recommended. If multiple pins are labeled V_{CC} , then a 0.01- μ F or 0.022- μ F capacitor is recommended for each V_{CC} because the V_{CC} pins are tied together internally. For devices with dual-supply pins operating at different voltages, for example V_{CC} and V_{DD} , a 0.1- μ F bypass capacitor is recommended for each supply pin. To reject different frequencies of noise, use multiple bypass capacitors in parallel. Capacitors with values of 0.1 μ F and 1 μ F are commonly used in parallel. The bypass capacitor must be installed as close to the power terminal as possible for best results.

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11 Layout

11.1 Layout Guidelines

Reflections and matching are closely related to the loop antenna theory but are different enough to be discussed separately from the theory. When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self-inductance of the trace, which results in the reflection. Not all PCB traces can be straight; therefore, some traces must turn corners. [Figure 7](#) shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

11.2 Layout Example

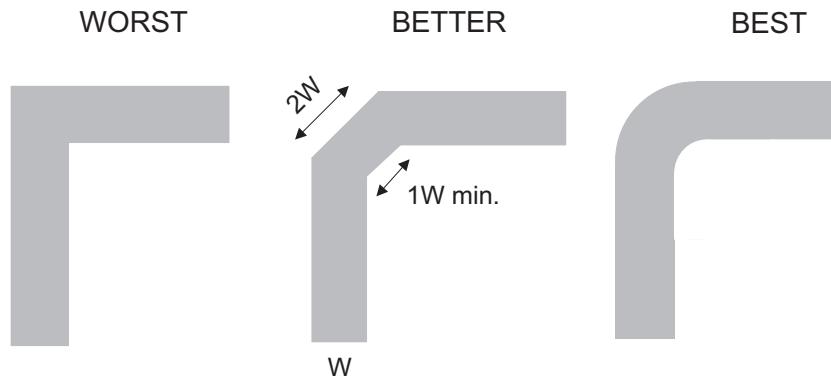


Figure 7. Trace Example

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#)
- *Selecting the Right Texas Instruments Signal Switch*, [SZZA030](#)

12.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.3 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.4 Electrostatic Discharge Caution

 These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74CB3Q3125DBQRE4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU125	Samples
74CB3Q3125DBQRG4	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU125	Samples
SN74CB3Q3125DBQR	ACTIVE	SSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU125	Samples
SN74CB3Q3125DGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	BU125	Samples
SN74CB3Q3125RGYR	ACTIVE	VQFN	RGY	14	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	BU125	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

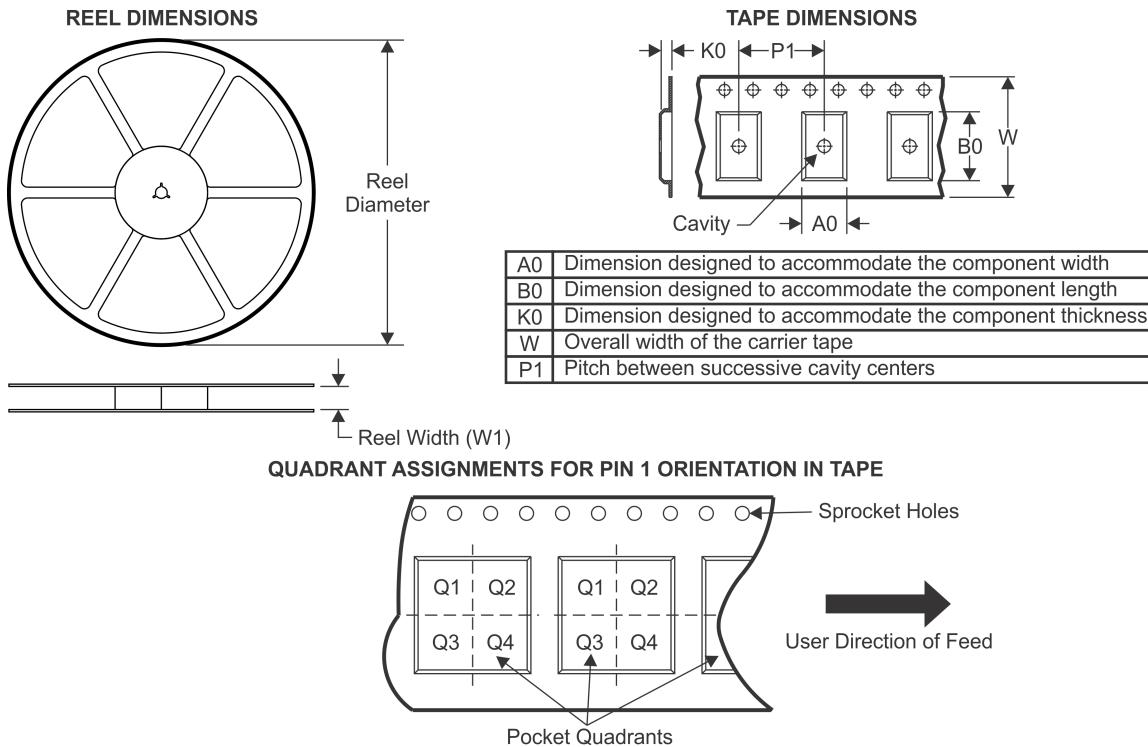
⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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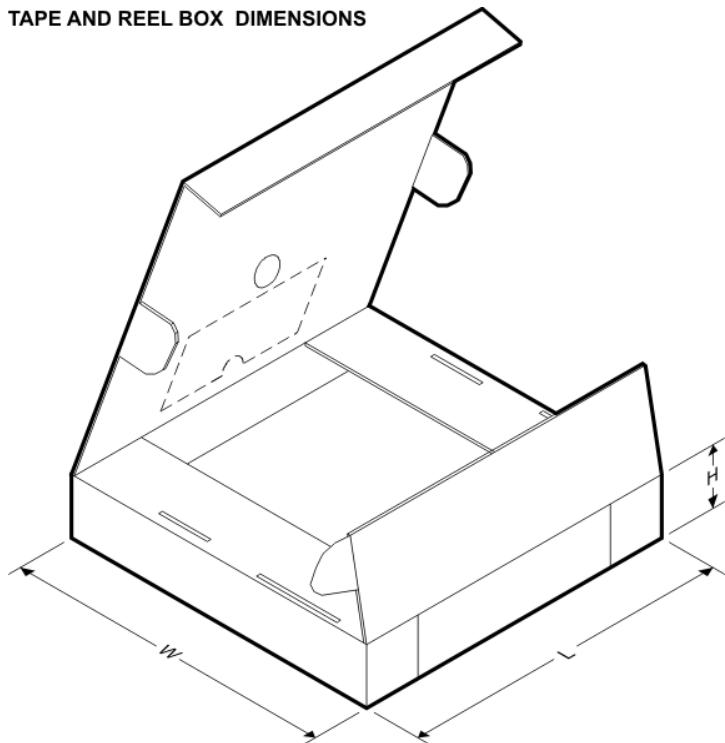
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CB3Q3125DBQR	SSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN74CB3Q3125DGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74CB3Q3125PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CB3Q3125RGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

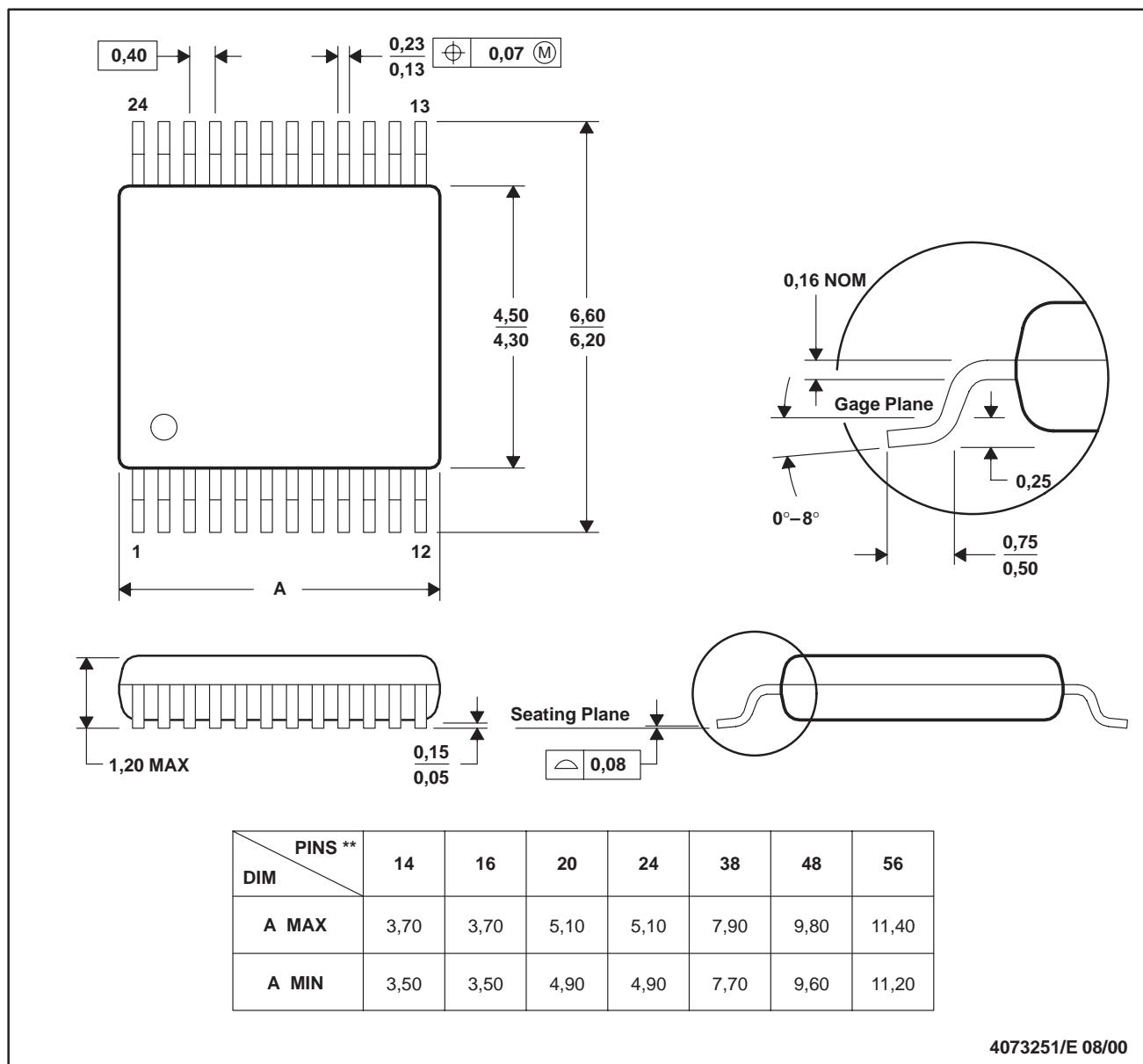
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CB3Q3125DBQR	SSOP	DBQ	16	2500	340.5	338.1	20.6
SN74CB3Q3125DGVR	TVSOP	DGV	14	2000	367.0	367.0	35.0
SN74CB3Q3125PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74CB3Q3125RGYR	VQFN	RGY	14	3000	367.0	367.0	35.0

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DGV (R-PDSO-G)**

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



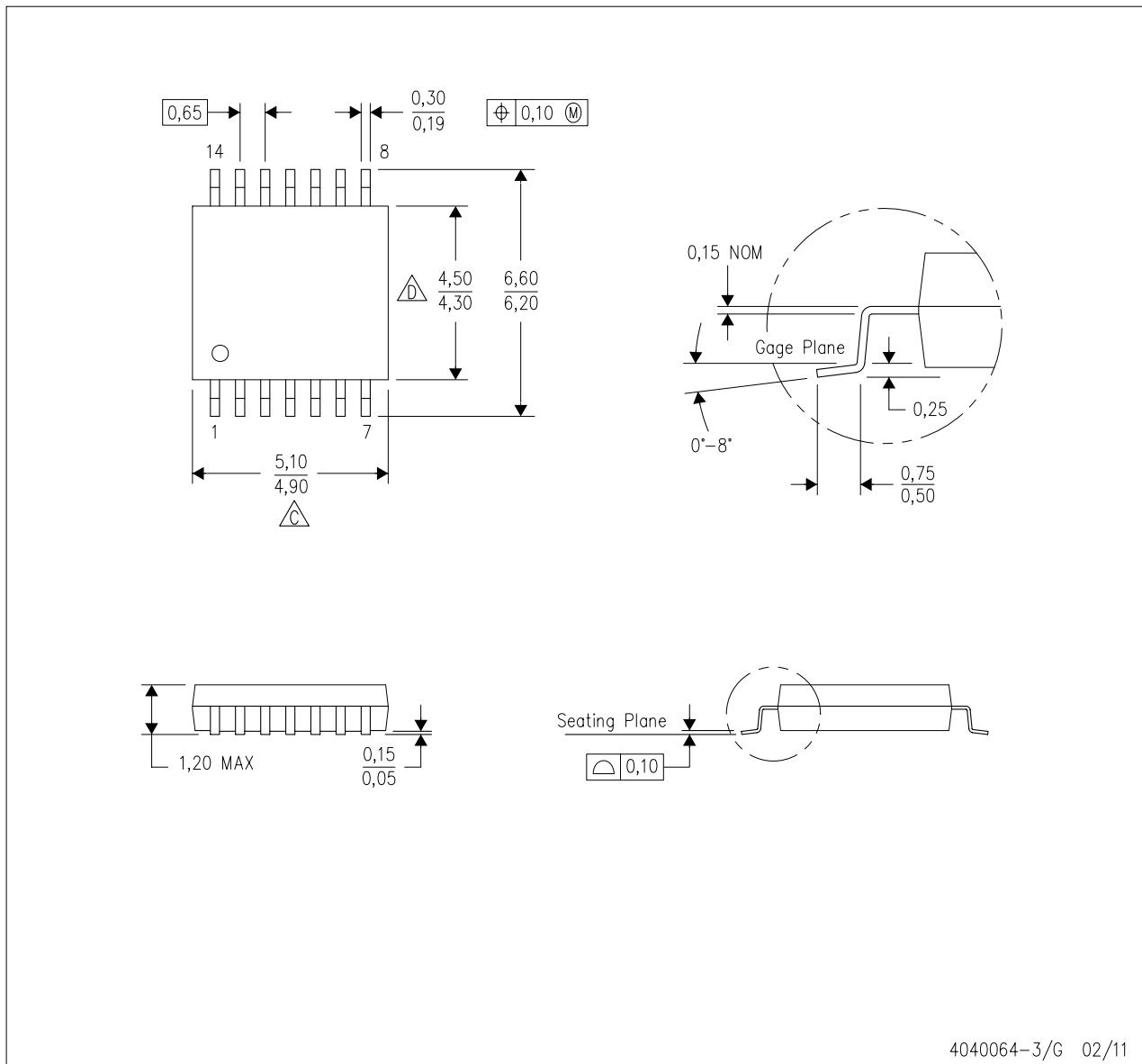
NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

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MECHANICAL DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

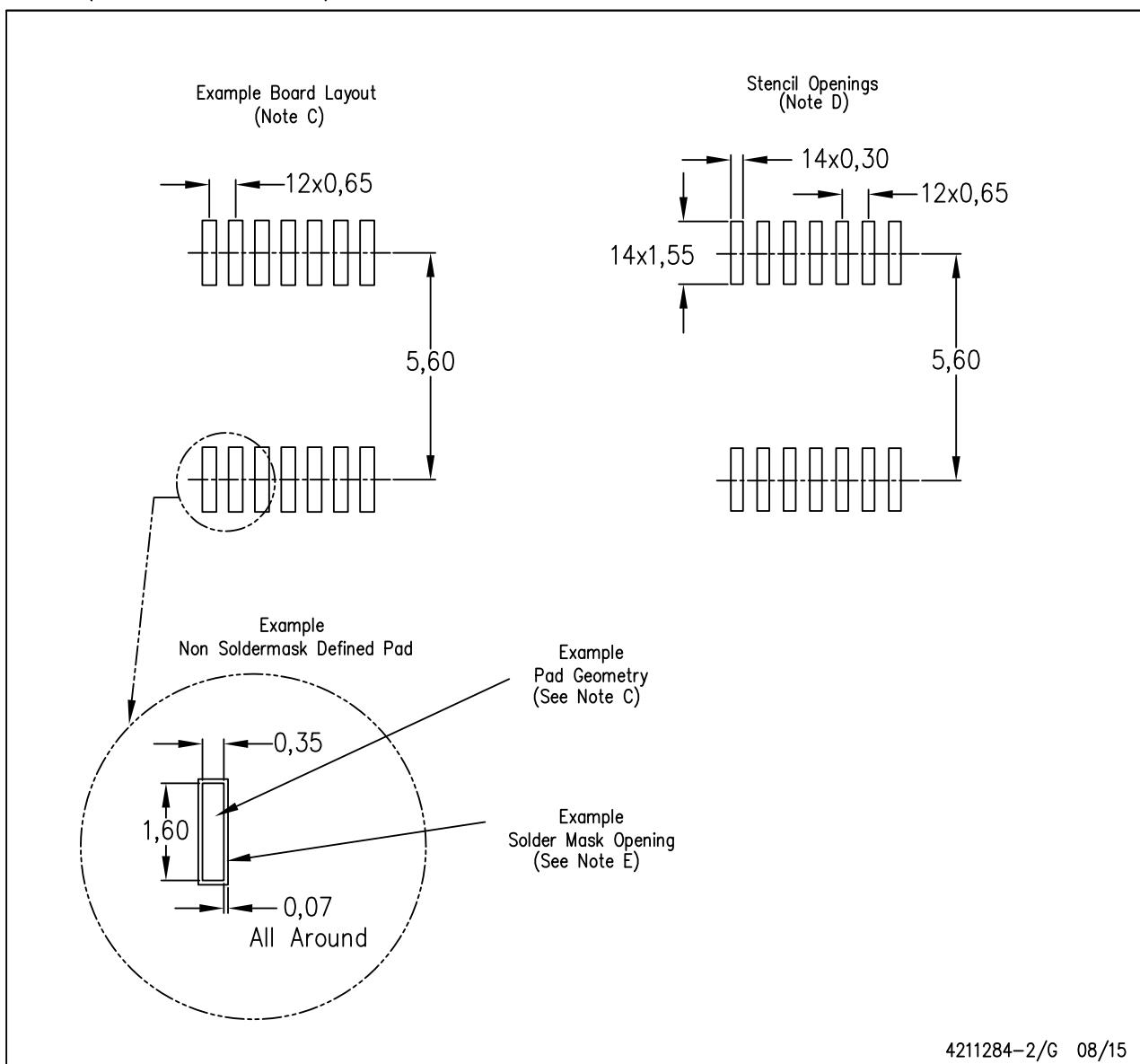
NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153

LAND PATTERN DATA

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



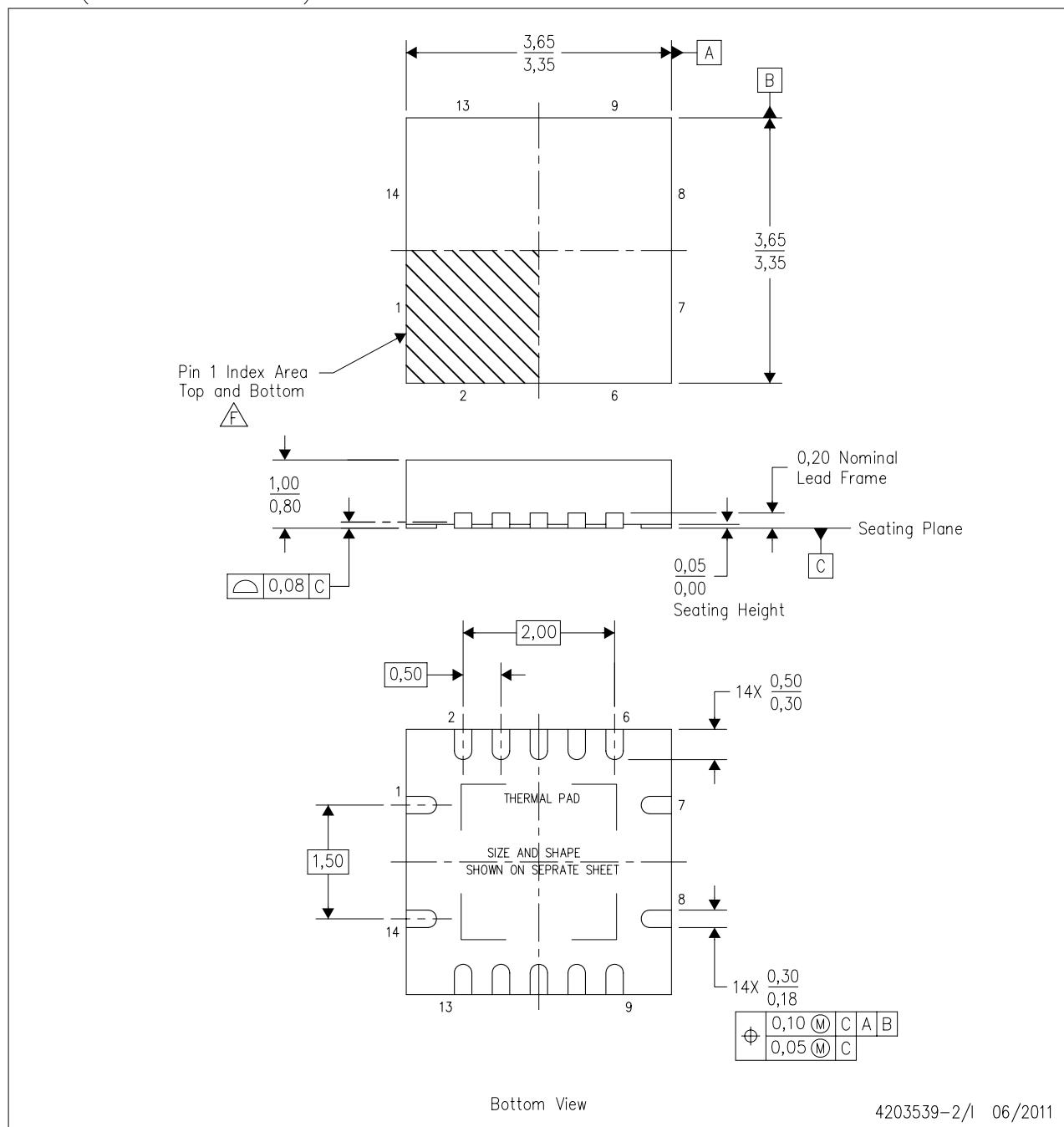
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- G. Package complies to JEDEC MO-241 variation BA.

THERMAL PAD MECHANICAL DATA

RGY (S-PVQFN-N14)

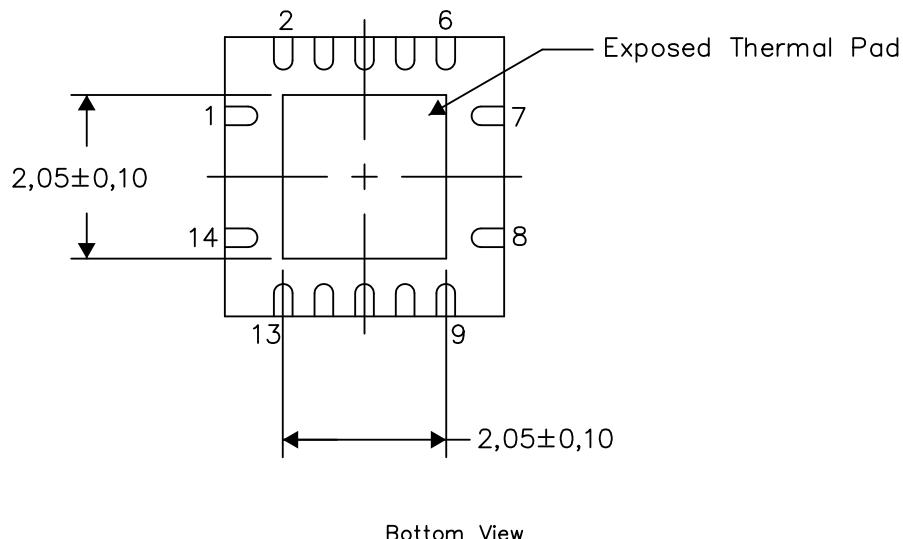
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



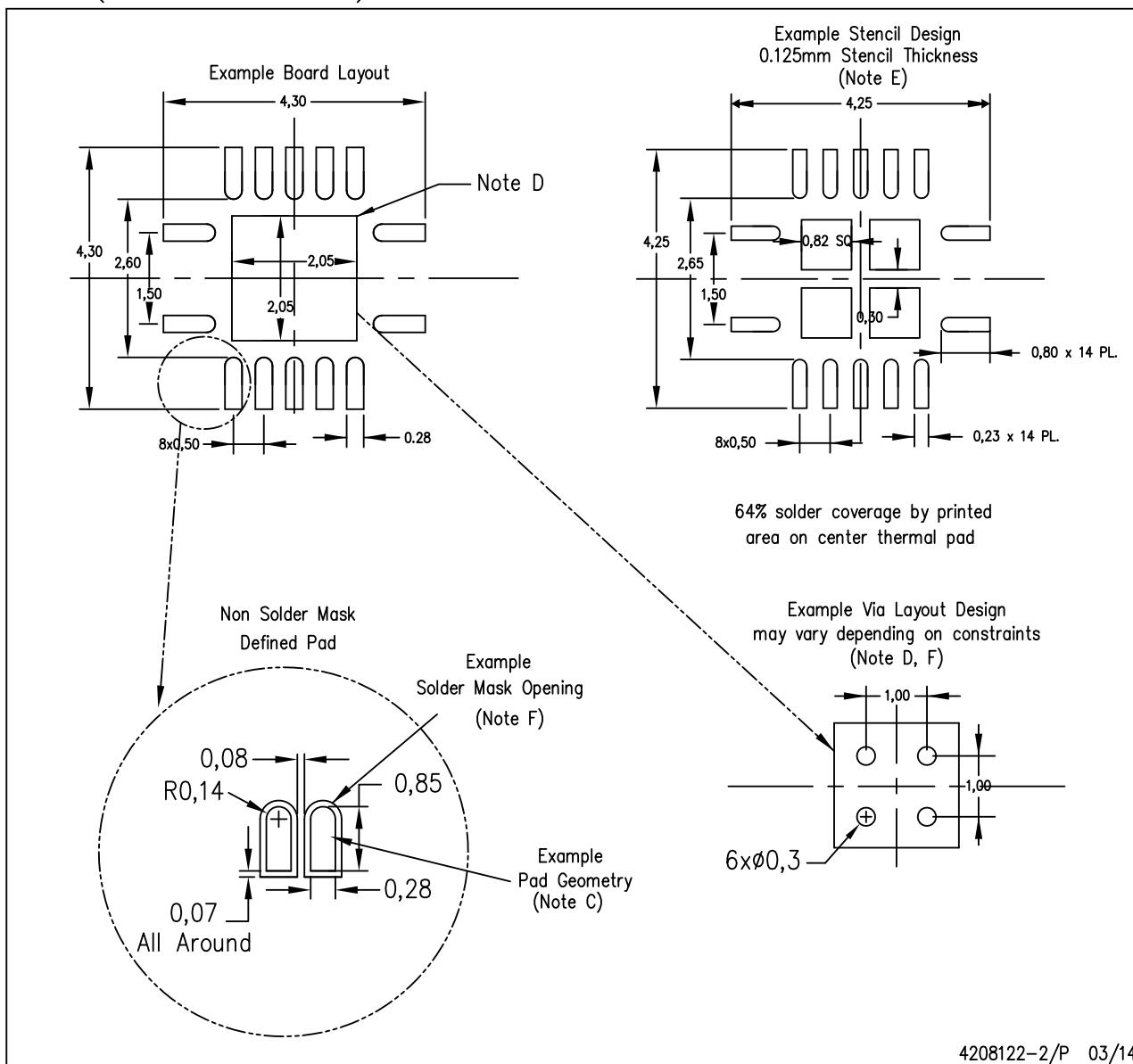
4206353-2/P 03/14

NOTE: All linear dimensions are in millimeters

LAND PATTERN DATA

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



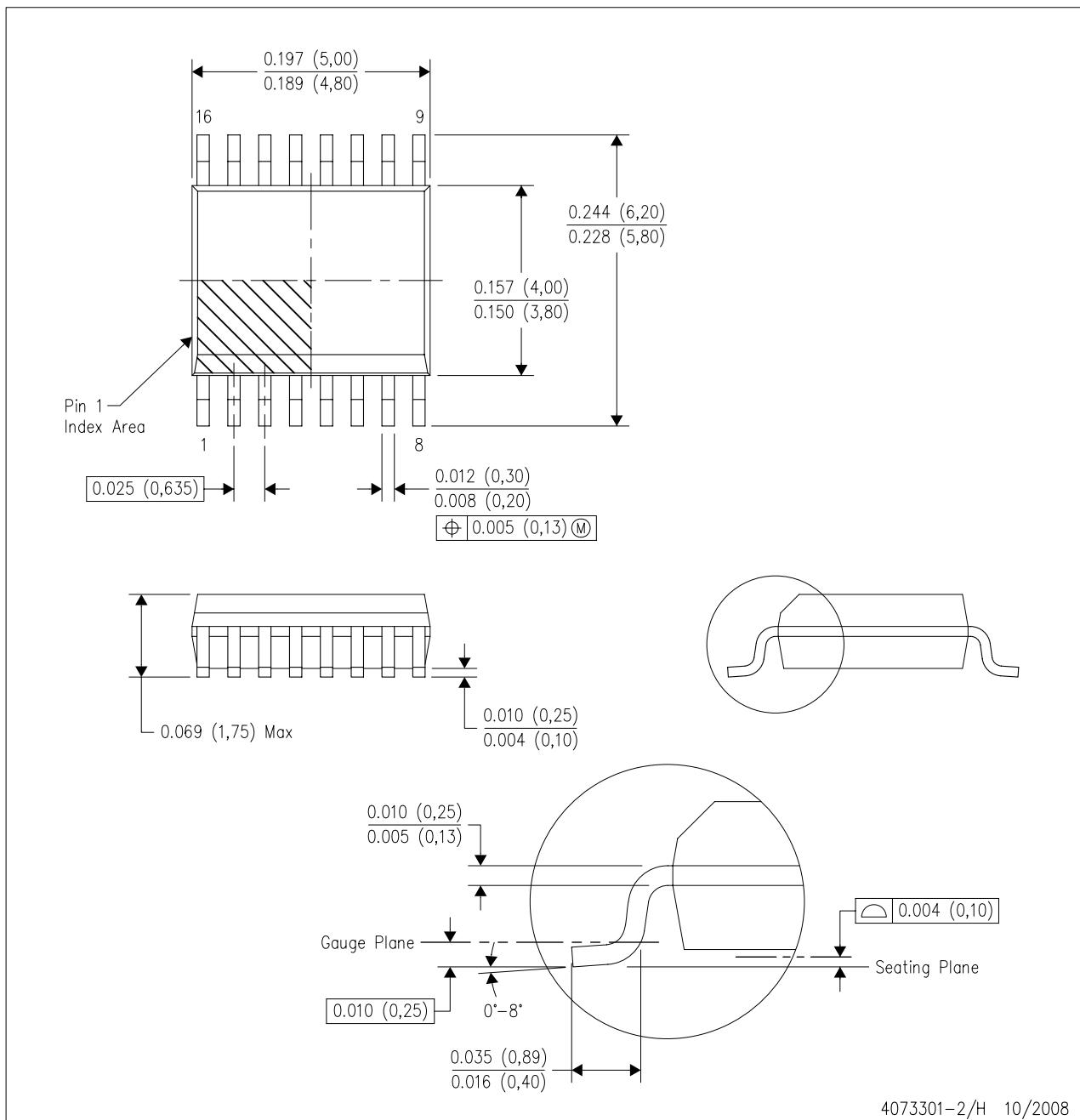
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
- Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

MECHANICAL DATA

DBQ (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



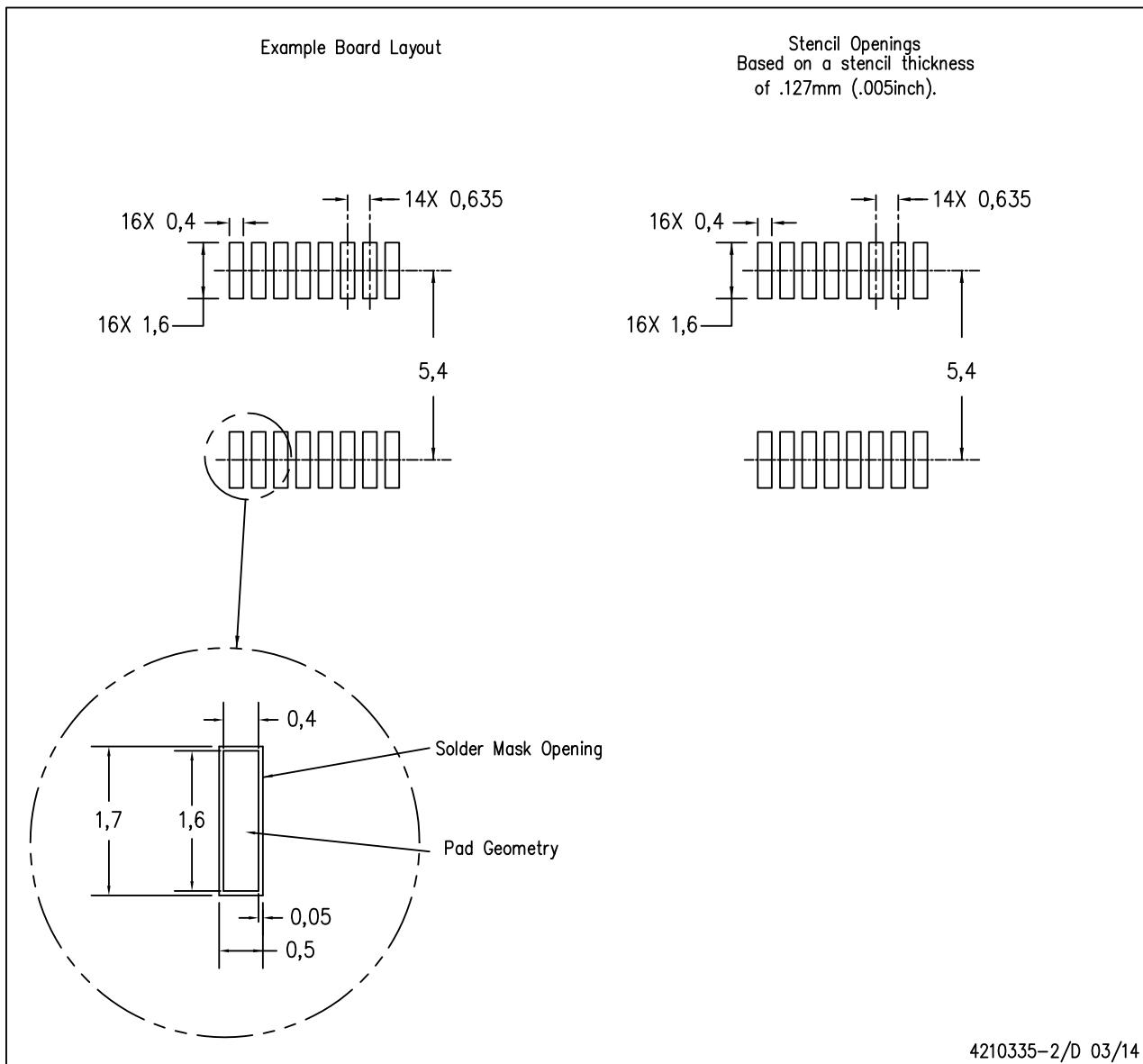
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
- Falls within JEDEC MO-137 variation AB.

LAND PATTERN DATA

DBQ (R-PDSO-G16)

PLASTIC SMALL OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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